

Asian IBIS Summit, Tokyo, Japan

# Simulation Technology for Memory Designers in DDR4/5

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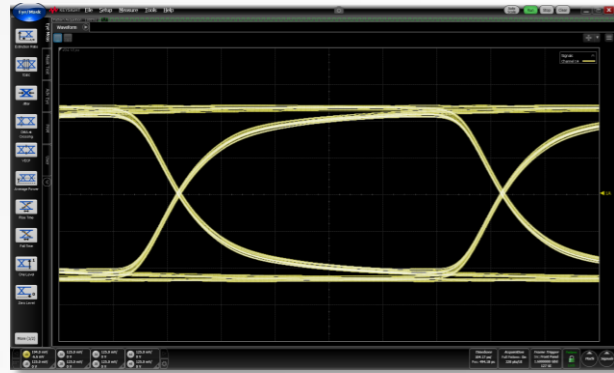
12 Nov. 2018

Keysight Technologies Japan K.K.

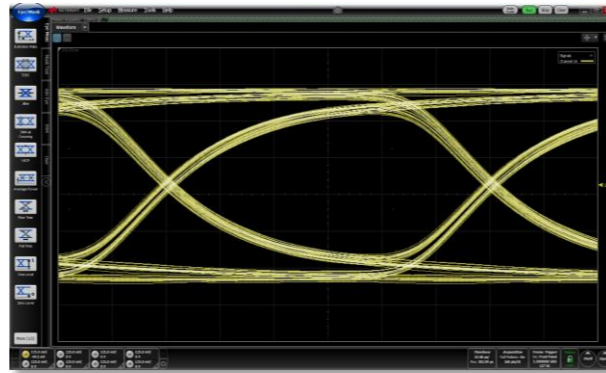


# DDR5 is coming

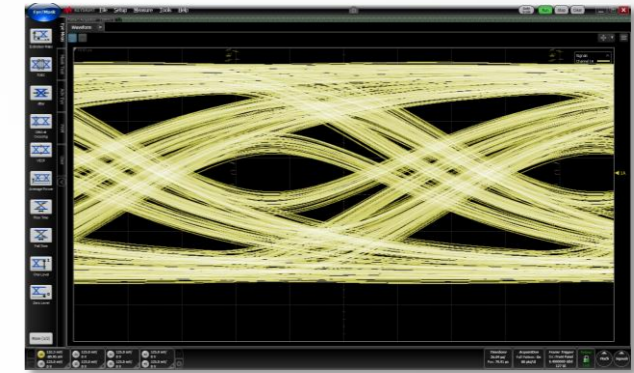
The data eye is closing



**1600**



**3200**



**6400**

Memory channel BW limited

Rj improving slowly

Xtalk effects increasingly severe

ISI



Jitter



Xtalk



Closed Eye

# Agenda

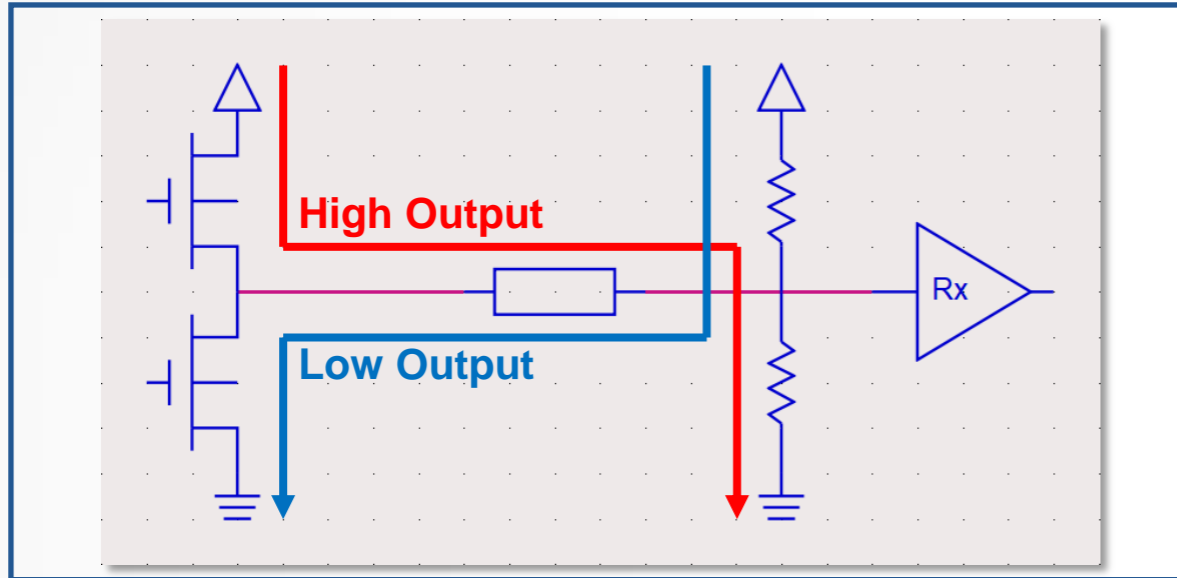
- DDR4 Highlights
- 4 challenges for memory designers in DDR4/5
- A Look at JEDEC's current DDR5 proposal
- How will we model DDR5 devices in simulation?
- A side-by-side comparison of some approaches for DDR5 simulation

# LP/DDR<sub>x</sub> Highlights

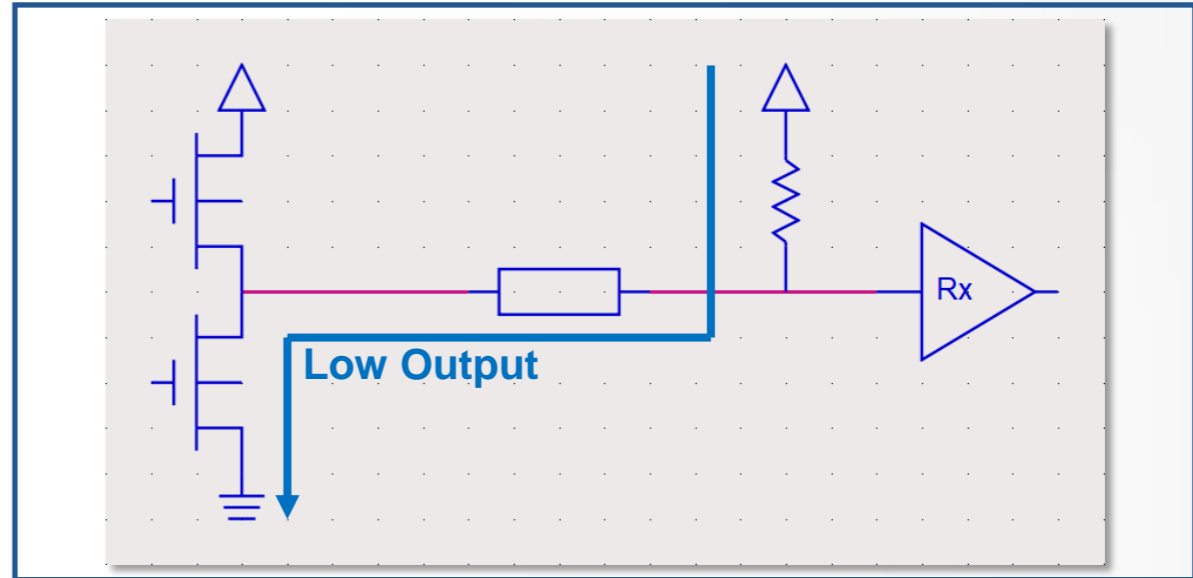
Specification	DDR3	DDR4	LPDDR4
Data Rate / Pin (Mbps)	800 - 2133	1600 - 3200	1333 - 4266
Bus Width	4, 8, 16	4, 8, 16	2, 4, 16, 32
Voltage	1.5 / 1.35	1.2	1.1
Vref	External Vref (=Vref/2)	Internal Vref	Internal Vref
Signal Evaluation	Setup/Hold time	Mask (considered BER)	
Data I/O	CTT (Center Tapped Termination)	POD (Pseudo Open Drain)	LVSTL (Low Voltage Swing Terminated Logic)

# LP/DDRx Highlights

DDR3 - CTT (Center Tapped Termination)

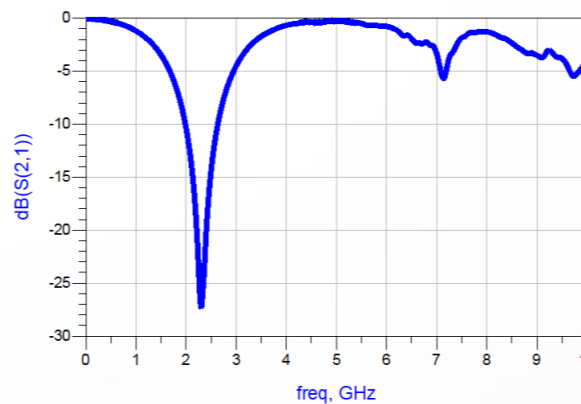
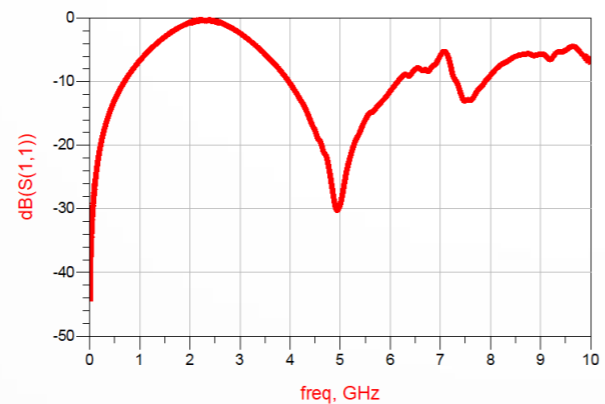
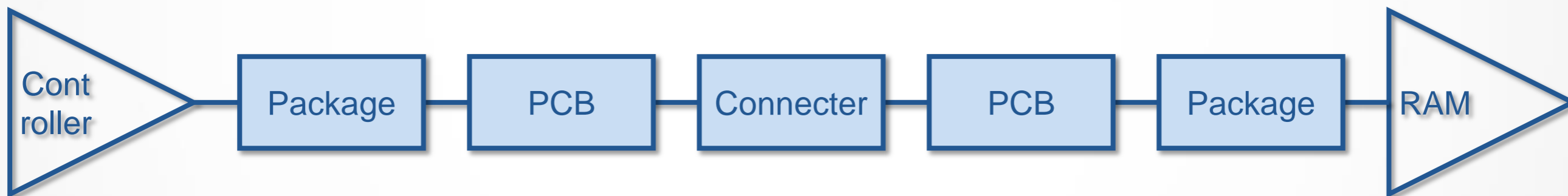
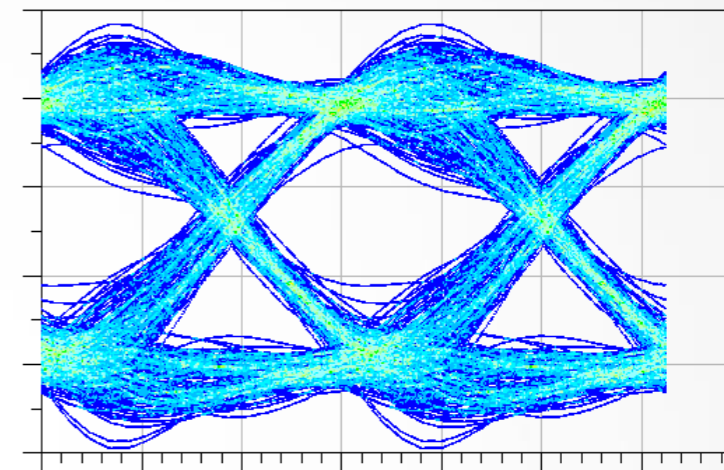
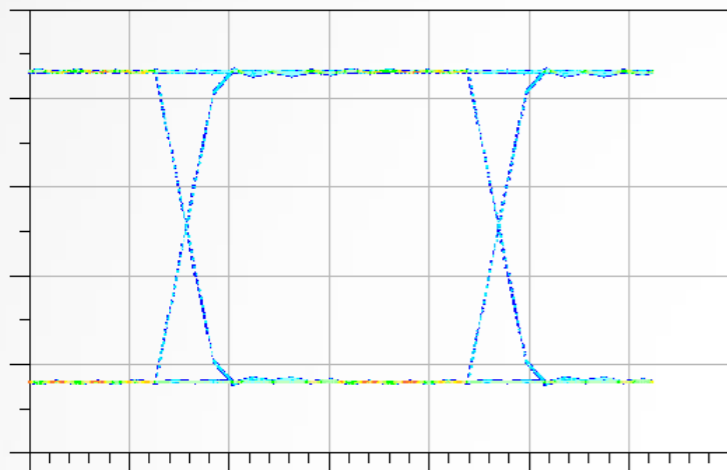


DDR4 - POD(Pseudo-Open Drain)



- Lower VDD voltage and Pseudo-Open Drain (POD) reduces power consumption by 40%.
- Internal VREF training performed within the IC receiver, to optimize VREF level. Retraining at regular intervals.
- Data lines are calibrated at the IC, to reduce their skew to the strobe.
- Data Bus Inversion (DBI).

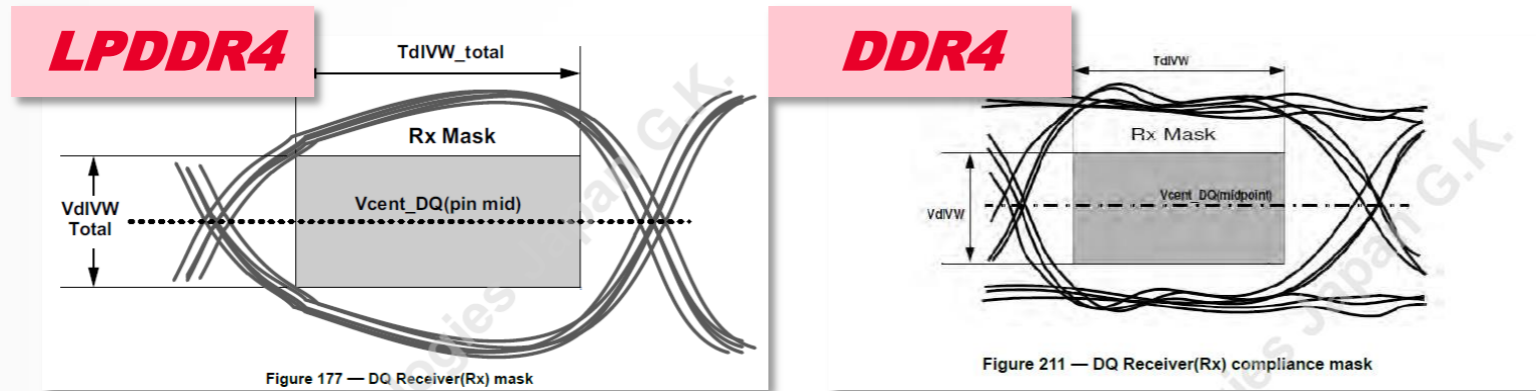
# Shrinking eye due to package, PCB and connectors



# Today's Disruption

The fuzzy eye takes over

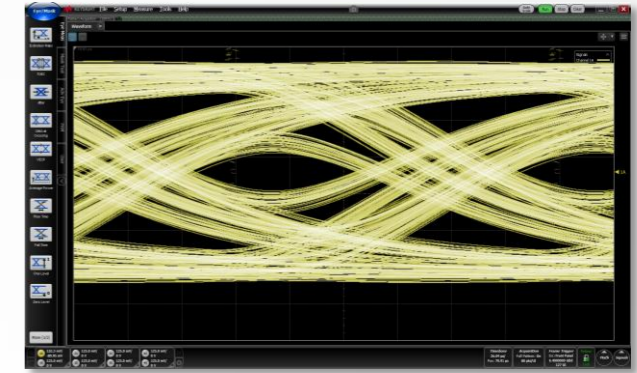
LP/DDR4 receiver requirements defined by masks instead of setup / hold and DC voltage swings



Source : JEDEC Standard JESD209-4B/JESD79-4B

- Simpler definition of DRAM requirements and system design.
- More compatible with LPDDR4 training procedures.
- Eliminates troublesome slew rate derating.
- Bit Error Rate (BER) spec recovers timing and noise margin.

Fundamental paradigm shift with DDR4



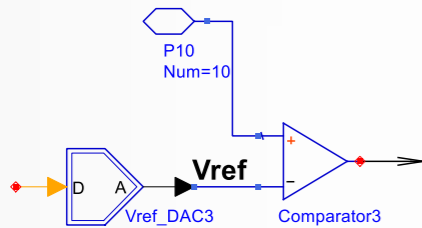
6400

# What is a mask ?

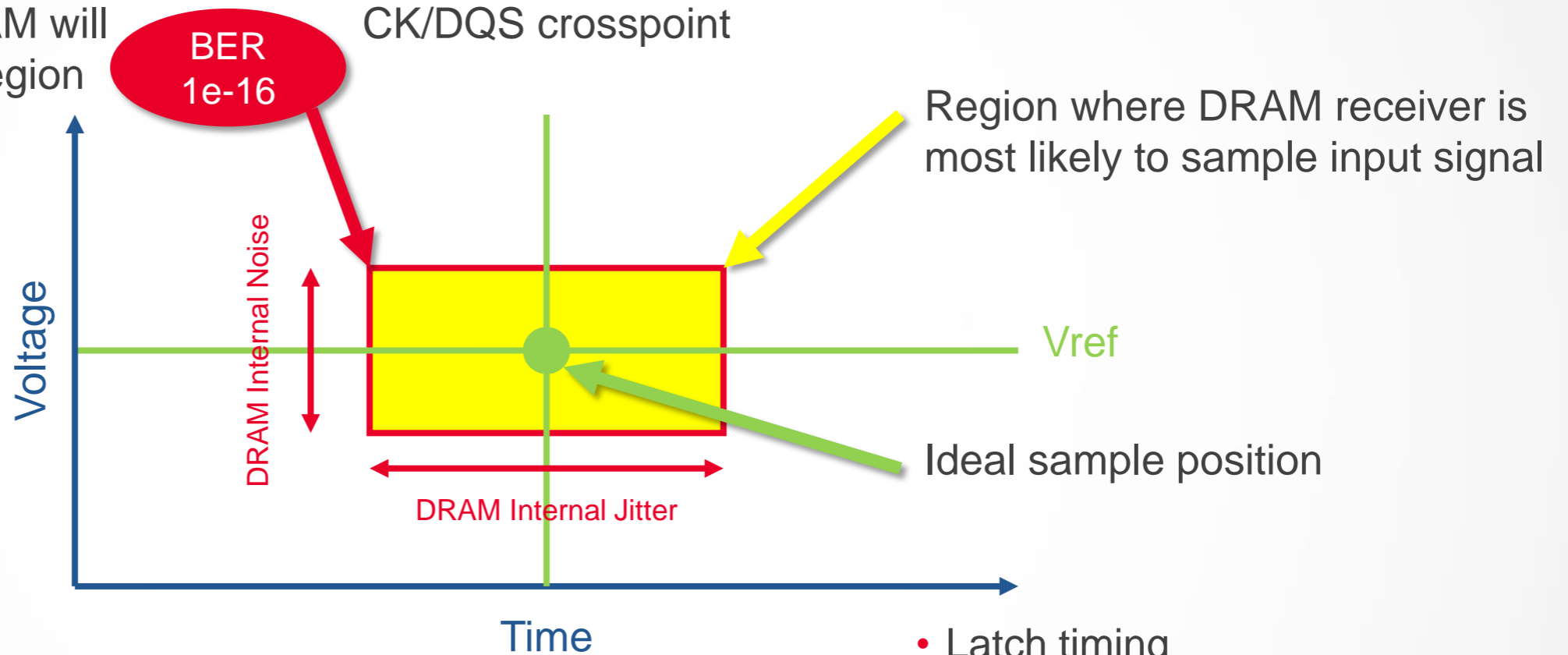
Source : JEDEC Standard JESD209-4B

NOTE 2 The design specification is a BER < TBD. The BER will be characterized and extrapolated if necessary using a dual dirac method.

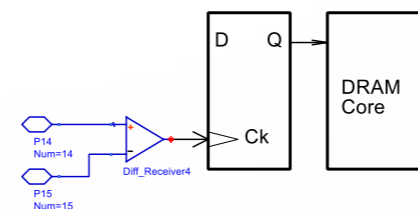
BER = Probability that DRAM will sample outside the mask region



- DAC quantization error
- Comparator hysteresis
- Comparator offset error
- Internal noise and crosstalk



- Latch timing
- Clock receiver hysteresis
- DRAM internal skews
- Internal noise converted to jitter





# Challenges for DDR4/DDR5

## Challenge #1

Timing margin will be further eroded by ISI and RJ;  
The Rx Mask becomes the contract between Controller and DRAM in order to achieve at least prescribed BER (1e-16 for DDR4).

Source : JEDEC Standard JESD209-4B

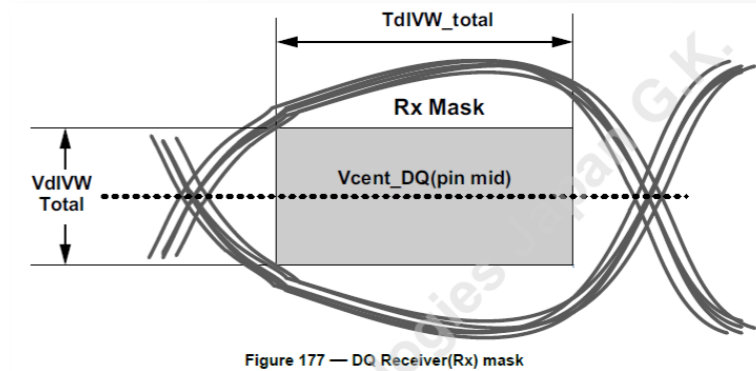
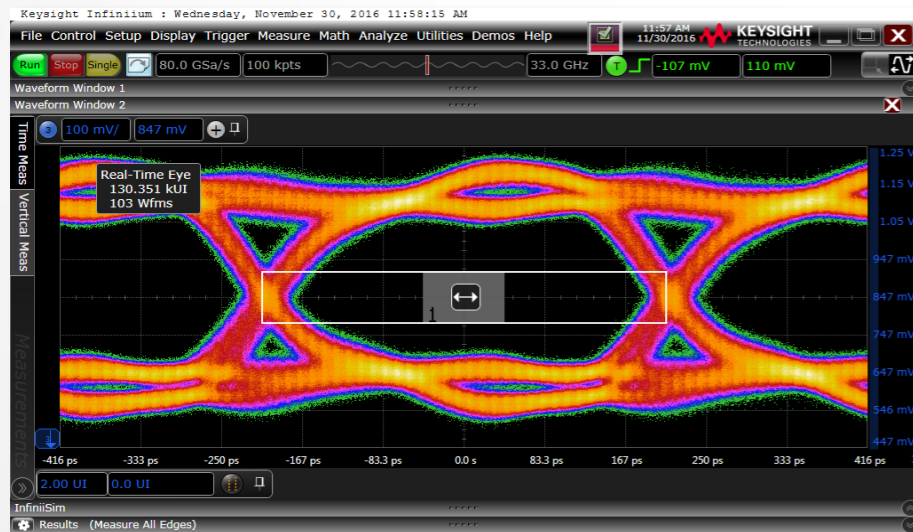
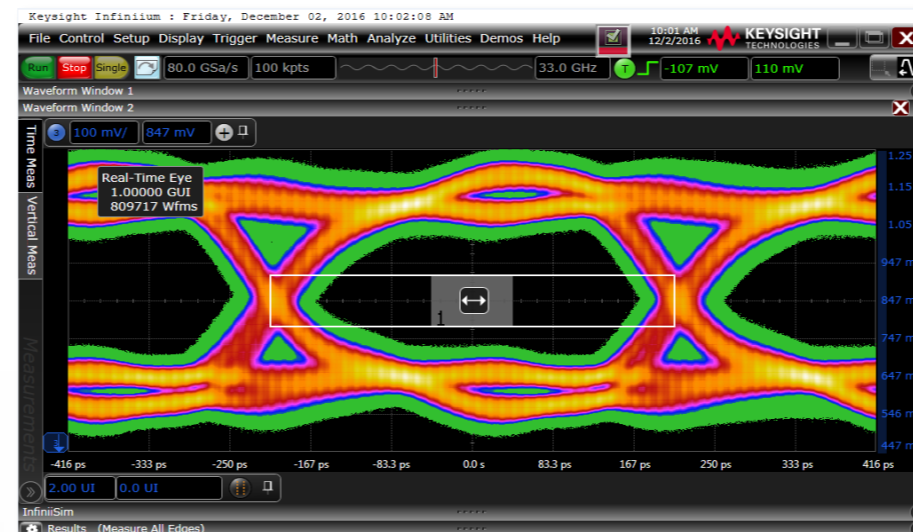


Figure 177 — DQ Receiver(Rx) mask

EH and EW keep shrinking at lower BER



**13,000bits**



**1e9bits**

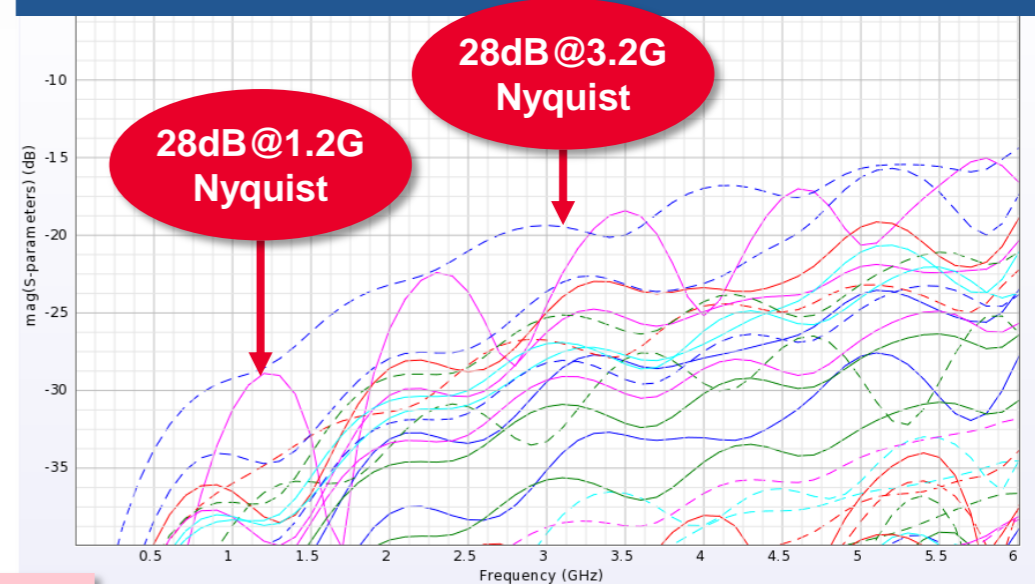
Number of UI	BER	Eye Width	Eye Height
1.3e5	7.69e-6	352.72 ps	310.9 mV
2.80e6	3.57e-7	347.52 ps	288.3 mV
6.31e7	1.58e-8	339.70 ps	275.8 mV
1.10e8	9.13e-9	339.06 ps	271.1 mV
1e9	1e-9	336.45 ps	265.6 mV

# Challenges for DDR4/DDR5

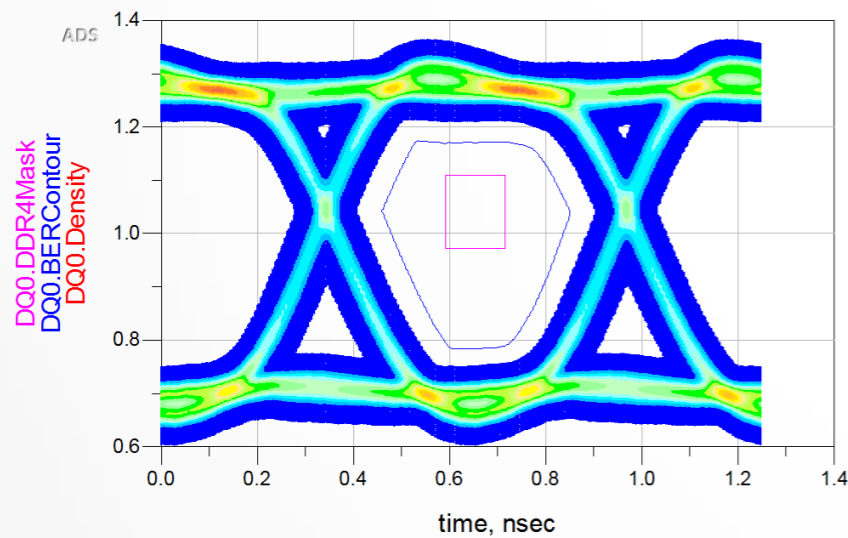
## Challenge #2

**Crosstalk.**  
As the speed increases, so does the amount of coupling between adjacent neighbors.

### NEXT & FEXT in PCB routing

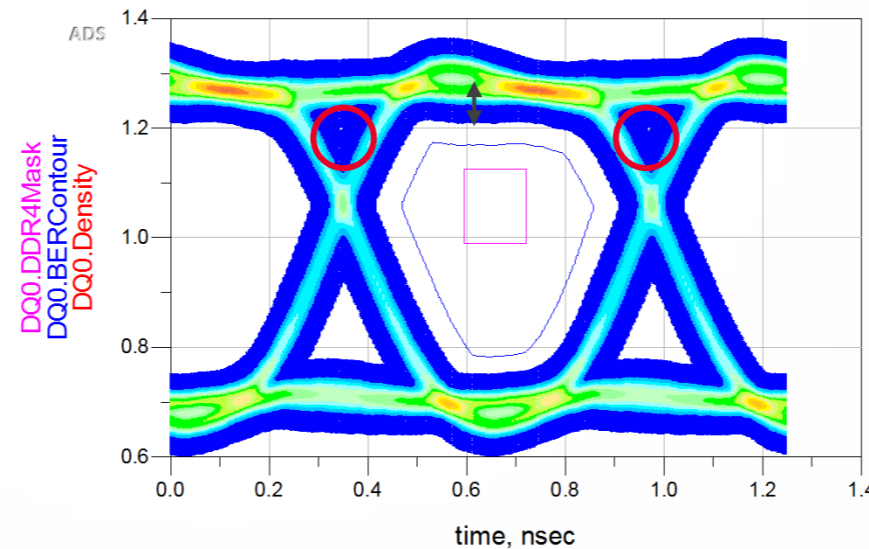


**DQ0**



**1600MHz DDR4**  
**No XTalk**

**DQ0**



**1600MHz DDR4**  
**Active Byte-Lane of**  
**DQ Signals (XTalk)**

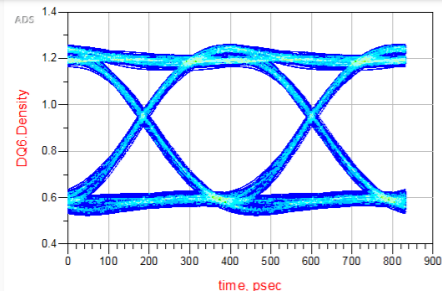
Even at slow speed grades  
the additional noise  
reduces margin to mask!

# Challenges for DDR4/DDR5

## Challenge #3

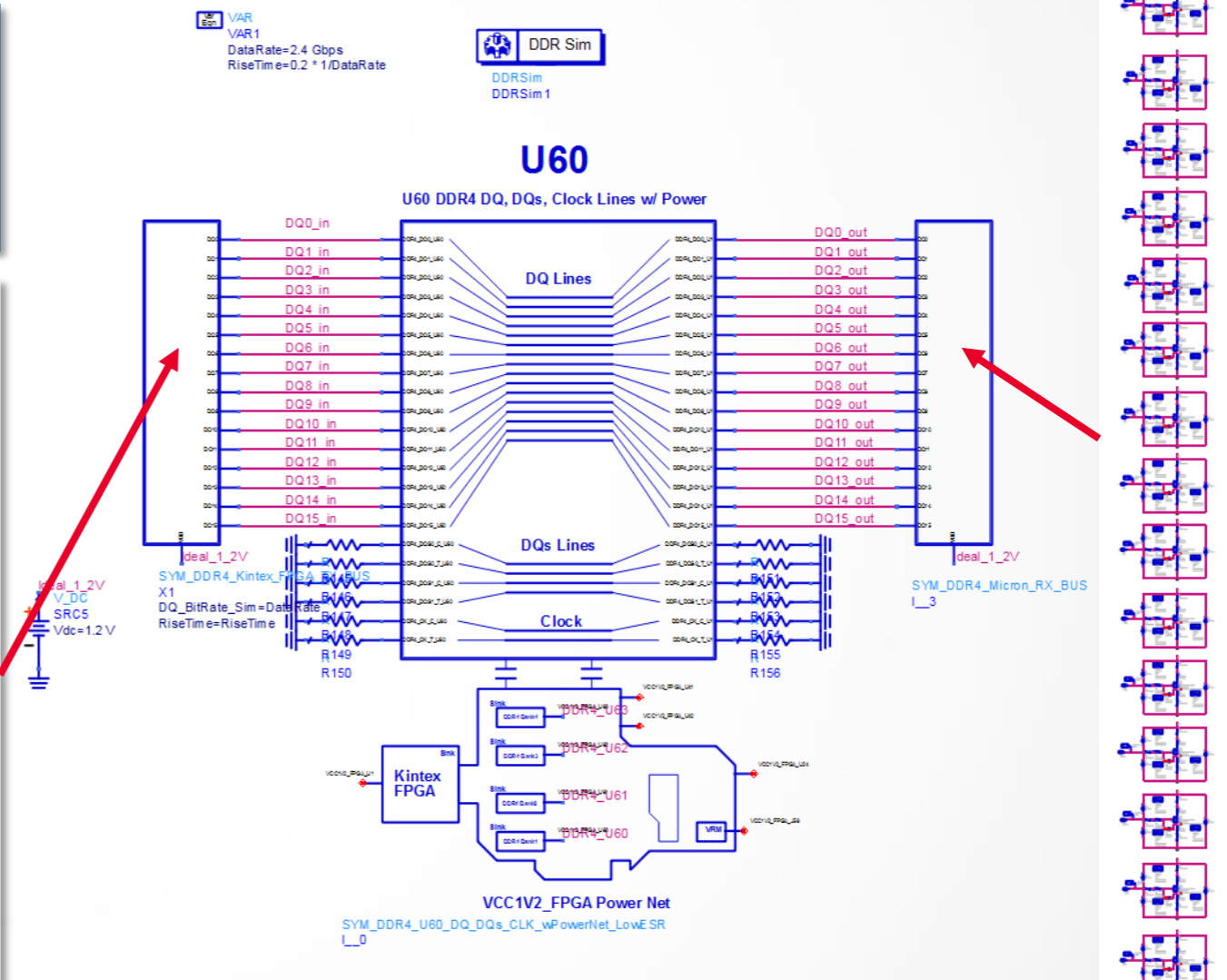
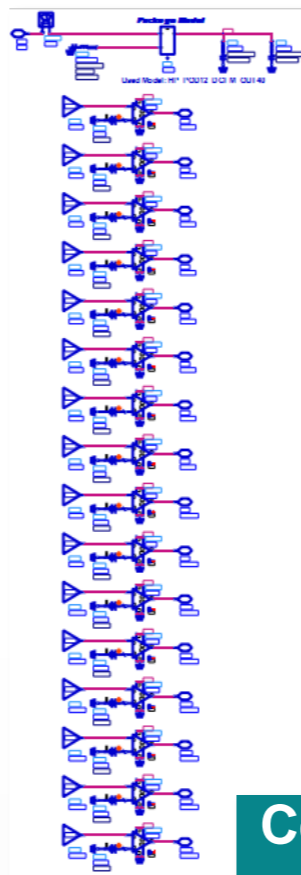
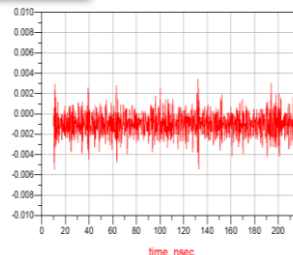
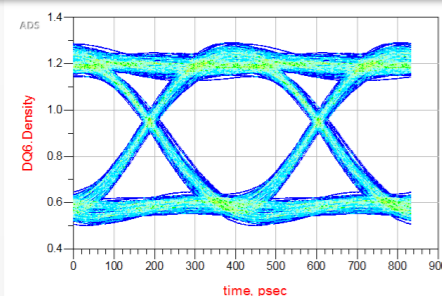
Additional jitter and amplitude noise due to Simultaneous Switching Noise (SSO/SSN) and other time-varying distortions.

**No PDN – Ideal VCCO**



measurement	DQ6 Summary
Height	510.0 m
Width	387.5 p

**With SSN**



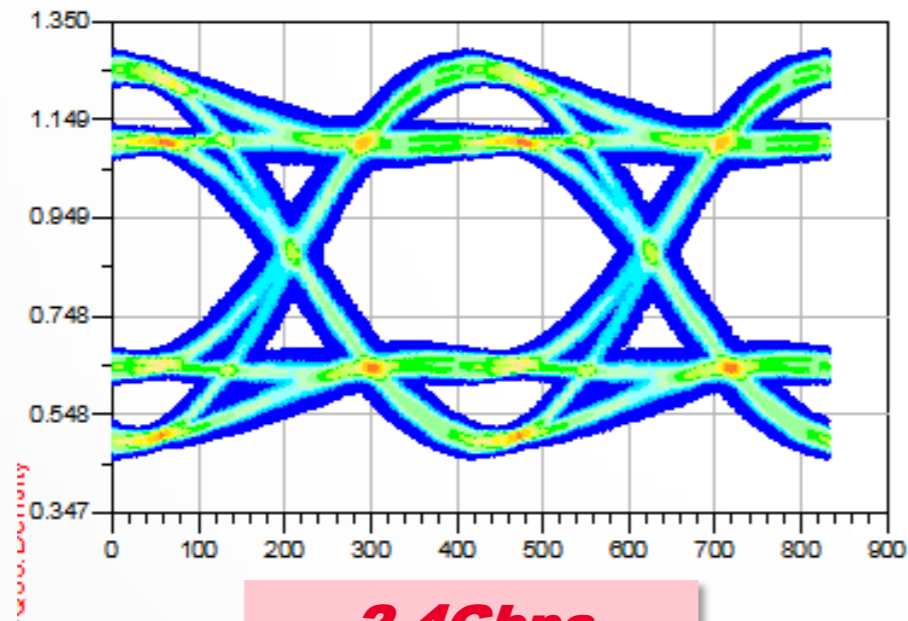
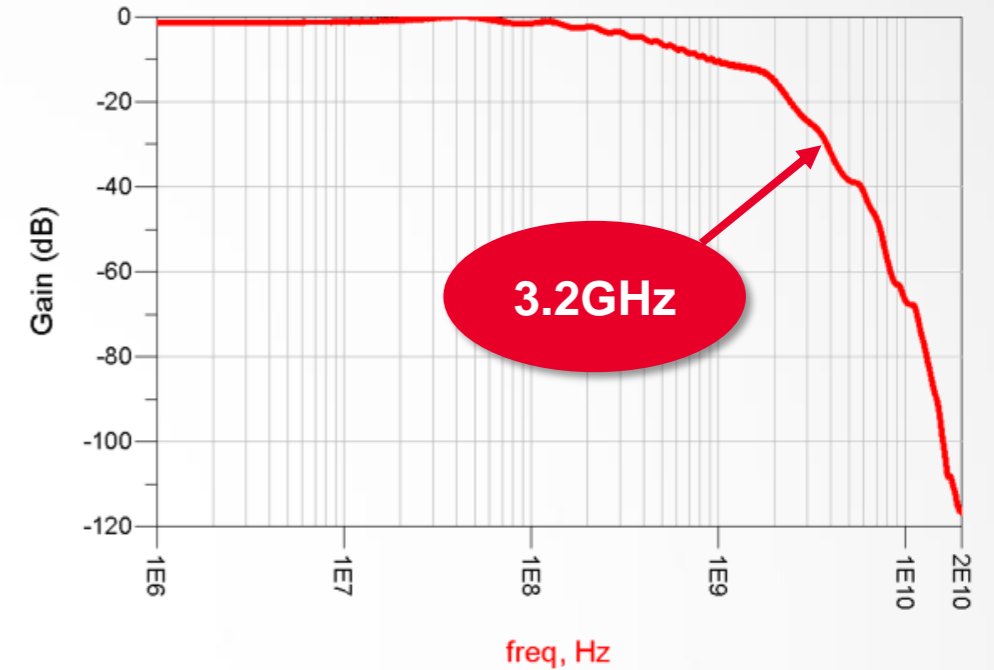
**Controller IBIS**

**RAM IBIS**

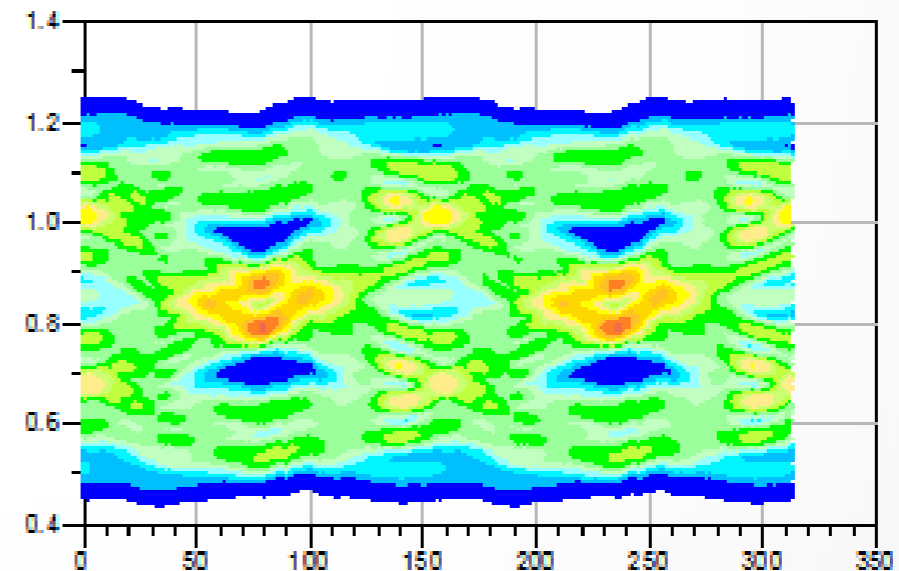
# Challenges for DDR5

## Challenge #4

Channel attenuation and ISI becomes more significant so tunable Equalization (De-emphasis, DFE) on Tx and Rx become necessary to deal with closed eyes.

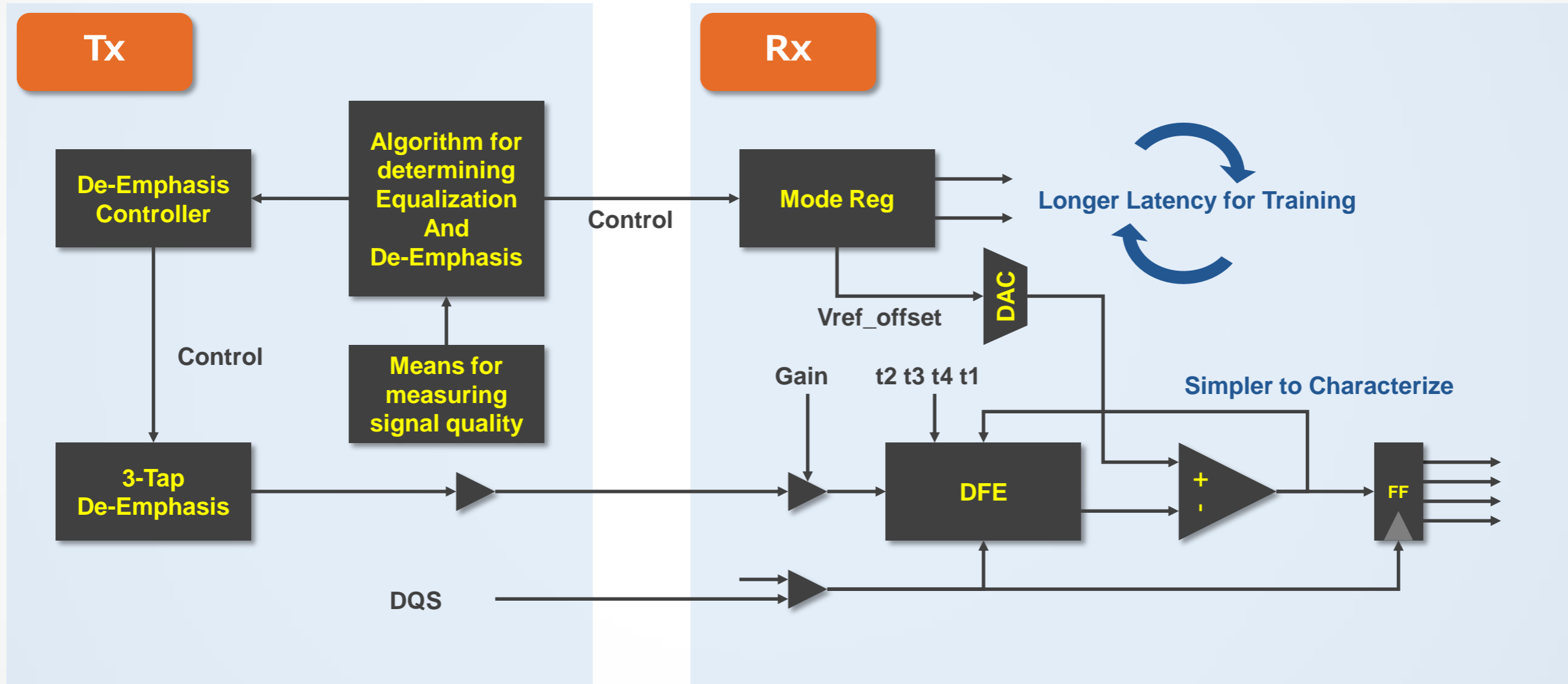


**2.4Gbps**

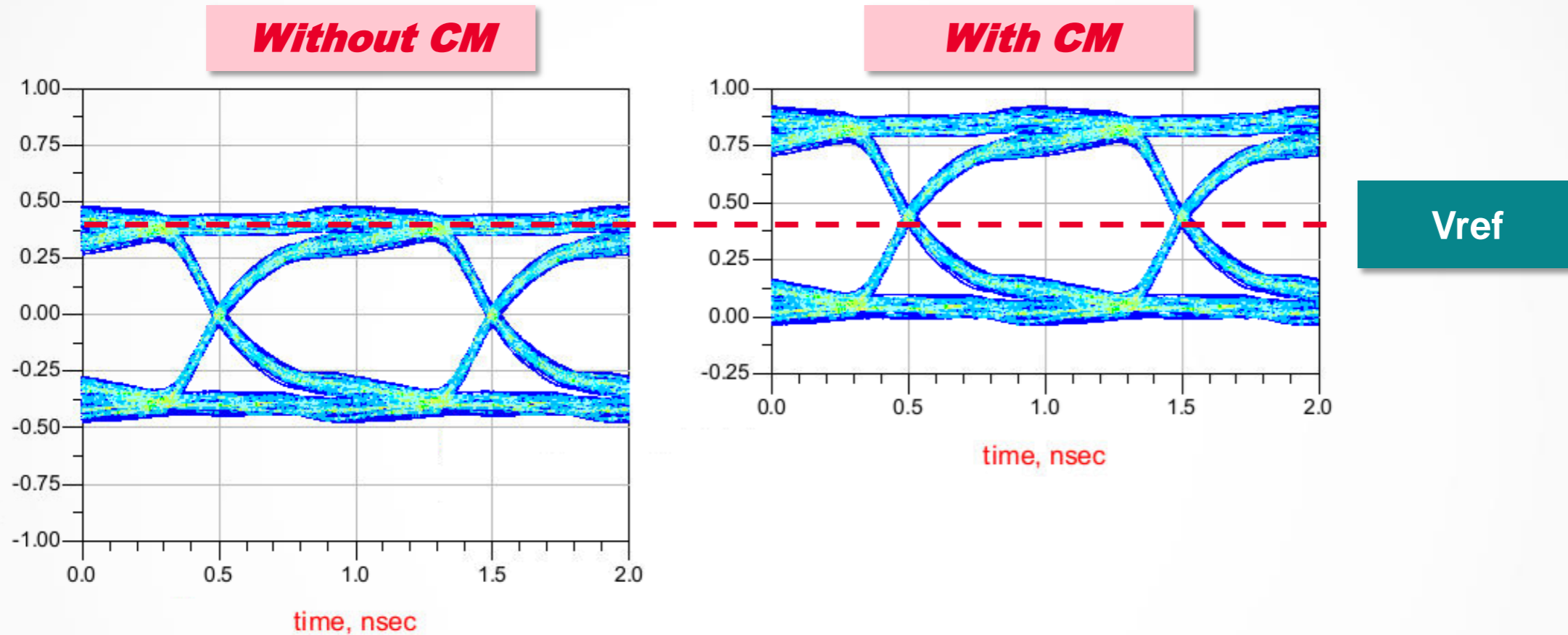


**6.4Gbps**

# DDR5 current proposal



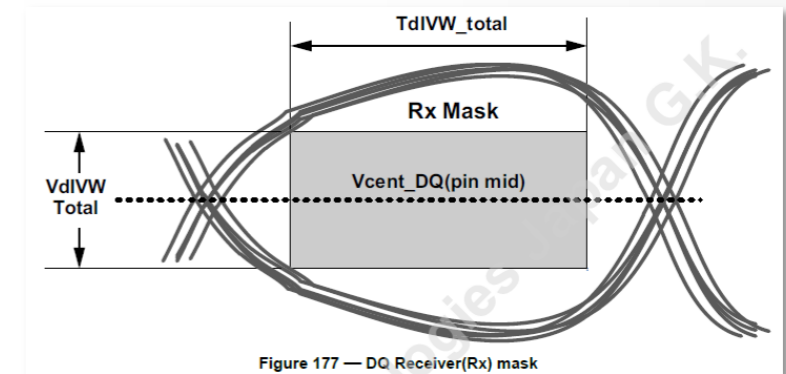
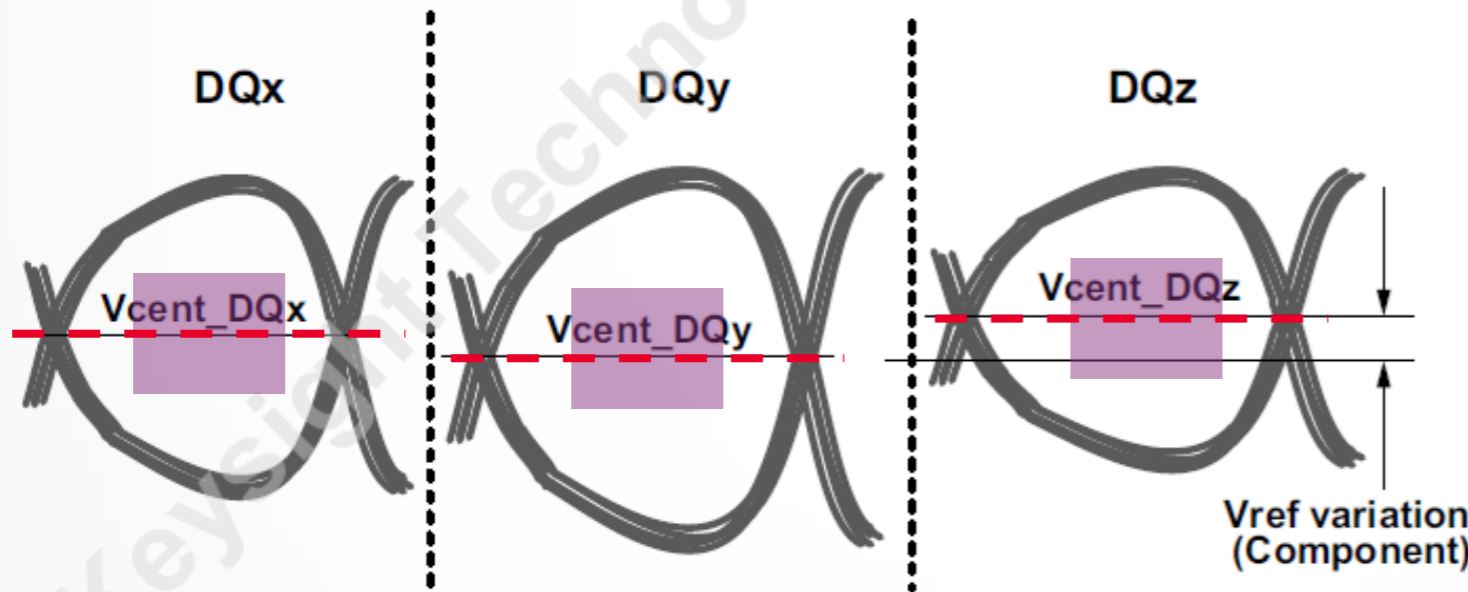
# Common-mode problem in IBIS-AMI



- IBIS-AMI only defines differential signal. Common-mode (CM) in single-ended (SE) signal is undefined and thrown away.
- IBIS-AMI waveform always centers at 0V. Signal level is off compared to Vref.

# Common-mode implications

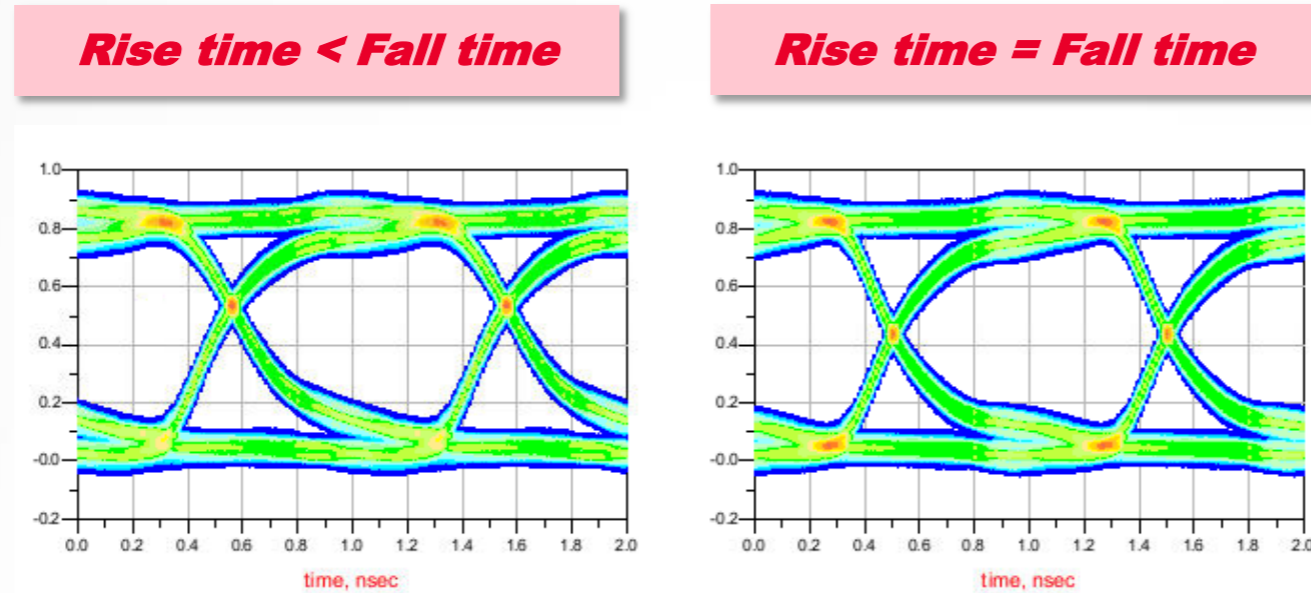
- One of the key implications of having the DC offset thrown away, is that margin to the **Rx BER Mask** requires **correct DC offsets** (to know where to place the mask).
- In other words, there is a single  $V_{ref}$  for the entire byte-lane. The spec defines the Rx Mask to be centered on  $V_{cent\_DQ}$ .



Source : JEDEC Standard JESD209-4B

$V_{cent\_DQ}$

# Asymmetric Rise and Fall Edges in Single-ended Signal



- Asymmetric rise and fall edges lead to data DCD jitter and crossing level shift, degrading timing and voltage margins with respect to Rx mask.
- Pull-up and pull-down behaviors depend on the analog channel and therefore must be included in analog channel response characterization.
- AMI has only one impulse response and can't capture difference between rise and fall edges. Response needs to be characterized separately for each edge.
- Asymmetry between rise and fall edges is much more severe in single-ended signal than in differential signal. It gets worse as data rate increases.
- With different responses for different edges, IBIS-AMI's convolution scheme is no longer applicable. Moreover, Tx GetWave output waveform becomes useless as a result.



# Current Proposals in the EDA Community

## DDR5 approaches

### Statistical DDR Bus

- Sim speed: Very Fast
- **Pros:**
  - Calculates **ultralow BER contours** (e.g. 1e-16) for Rx BER mask
  - **Correct Eye Shape** and **DC offset!**
  - Finds **optimal DFE tap weights**
  - In the future can be extended to support Bit-by-Bit mode
  - Simplicity of EQ modeling
- **Cons:**
  - **No non-linear or time-varying effects.**
  - IP protection not standardized

### IBIS-AMI

- Sim speed: Fast
- **Pros:**
  - Well-defined **model interface** / concealment of IP
  - Can support both **statistical** and **bit-by-bit** simulations
  - Future possibility for back-channel adaption
- **Cons:**
  - **Incorrect Eye-shape** and DC offset
  - **Complexity** of modeling
  - **No non-linear or time-varying effects**

### SPICE + Verilog-A

- Sim Speed: Very Slow
- **Pros:**
  - Captures all **non-linear and time-varying effects**
- **Cons:**
  - **Impractical** to simulate enough bits to ever extrapolate BER contours accurately to 1e-16!
  - Sharing of **encrypted HSPICE** models requires HSPICE
  - Verilog-A implementation **complexity** and requires compiled Verilog-A for IP protection (not supported in all tools)
  - Simulator support for **sweeps?**



**KEYSIGHT**  
**TECHNOLOGIES**

4.90221